# mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# RS3A/B - RS3M/B

## **3.0A SURFACE MOUNT FAST RECOVERY RECTIFIER**

### Features

- Glass Passivated Die Construction
- Fast Recovery Time for High Efficiency
- Low Forward Voltage Drop and High Current Capability
- Surge Overload Rating to 100A Peak
- Ideally Suited for Automatic Assembly
- Plastic Material: UL Flammability Classification Rating 94V-0

### Mechanical Data

- Case: Molded Plastic
- Terminals: Solder Plated Terminal -Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- SMB Weight: 0.09 grams (approx.)
- SMC Weight: 0.20 grams (approx.)

	Α	3.30
	В	4.06
	С	1.96
•	D	0.15
∎ <b>–</b> D	Е	5.00
n n	G	0.10
	н	0.76
	J	2.00
		A B C D C D C D C D C D C D C D C D C D C

	SI	ЛB	SMC			
Dim	Min	Max	Min	Max		
Α	3.30	3.94	5.59	6.22		
В	4.06	4.57	6.60	7.11		
С	1.96	2.21	2.75	3.18		
D	0.15	0.31	0.15	0.31		
Е	5.00	5.59	7.75	8.13		
G	0.10	0.20	0.10	0.20		
н	0.76	1.52	0.76	1.52		
J	2.00	2.62	2.00	2.62		
All Dimensions in mm						

AB, BB, DB, GB, JB, KB, MB Suffix Designates SMB Package A, B, D, G, J, K, M Suffix Designates SMC Package

#### Maximum Ratings and Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	RS3 A/AB	RS3 B/BB	RS3 D/DB	RS3 G/GB	RS3 J/JB	RS3 K/KB	RS3 M/MB	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Average Rectified Output Current $@ T_T = 75^{\circ}C$	lo	3.0						А	
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	100				А			
Forward Voltage @ I <sub>F</sub> = 3.0A	V <sub>FM</sub>	1.3						V	
Peak Reverse Current@ T <sub>A</sub> = 25°Cat Rated DC Blocking Voltage@ TA = 125°C	I <sub>RM</sub>	5.0 250					μΑ		
Maximum Recovery Time (Note 3)	t <sub>rr</sub>	150 250 500		00	ns				
Typical Junction Capacitance (Note 2)	Cj	50			pF				
Typical Thermal Resistance Junction to Terminal (Note 1)	R <sub>0JT</sub>	т 25			K/W				
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	rg -65 to +150			°C				

Notes: 1. Thermal resistance: junction to terminal, unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pad as heat sink.

- 2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
- 3. Reverse recovery test conditions:  $I_F$  = 0.5A,  $I_R$  = 1.0A,  $I_{rr}$  = 0.25A. See figure 5.



Fig. 5 Reverse Recovery Time Characteristic and Test Circuit